

# High $Q$ Antisymmetric Mode Lithium Niobate MEMS Resonators With Spurious Mitigation

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**Abstract**—This paper reports on the demonstrations of first-order antisymmetric Lamb wave (A1) mode resonator as a new platform for front-end filtering of the fifth-generation (5G) wireless communication. The sub-6 GHz resonance in this work is achieved by employing the A1 mode in the micromachined Y-cut Lithium Niobate (LiNbO<sub>3</sub>) thin films. The spurious modes mitigation is achieved by optimizing the distribution of the electric field. The demonstrated figure-of-merit (FoM =  $Q \cdot k_t^2$ ) of 435 marks the first time that a new resonator technology with the FoMs exceeds those of surface acoustic wave (SAW) resonators and thin-film bulk acoustic resonators (FBARs) in the sub-6 GHz (1-6 GHz) frequency range. [2019-0241]

**Index Terms**—5G, IoT, Sub-6 GHz, acoustic resonator, lithium niobate, MEMS, spurious suppression.

## I. INTRODUCTION

IN RESPONSE to customers' demand for more mobile video streaming, cloud computing, virtual reality, and Internet-of-Things (IoT) applications, the global mobile data traffic is projected to increase by 45% per year in the next decade [1]–[3]. To keep up with the explosion of data, wireless providers around the globe plan to resort to the fifth-generation (5G) for overcoming the limitations of existing wireless networks (4G). In contrast to 4G, 5G will involve significantly expanded capacity via accessing larger physical bandwidths and deploying new technologies capable of such. To attain the large physical bandwidths while co-existing with incumbent wireless applications, 5G networks will take on either an unallocated spectrum at beyond 4G frequencies or spectrum that can be repurposed. Recent releases from various wireless standardization organizations (e.g., 3GPP) have shown the spectrum allocations around the world converging to either the sub-6 GHz spectrum where physical bandwidths are ranging from 20 MHz to 600 MHz, or the millimeter-wave (mm-wave) spectrum (several bands in Ka-band) where close to 1 GHz bandwidths are accessible [4], [5]. While the millimeter-wave frequencies are certainly less crowded and are more available, various outstanding challenges (e.g., spatial filtering, and power efficiency) have to be addressed before they are ready

for prime time. These technological challenges associated with mm-wave imply that mobile operators are likely to rely heavily on the sub-6 GHz spectrum for the initial 5G deployment and certain mission-critical applications for its high reliability and low latency.

Although the sub-6 GHz systems are considered less difficult because their front-ends are likely to feature a similar architecture to LTE systems and several front-end building blocks can be readily scaled up in frequency from their 4G counterparts, they are not without their own challenges. One key challenge arises from the significant increase in fractional bandwidths (FBW) transitioning from 4G to 5G. LTE bands, which have physical bandwidths ranging from 3 to 20 MHz at a center frequency from 0.4 to 3.7 GHz, have FBW less than 4% [6], [7]. On the other hand, 5G bands can end up demanding an FBW as high as 24% (e.g., 3.3 GHz – 4.2 GHz) [4]. Such a large FBW greatly challenges the capabilities of the incumbent mobile front-end filtering solution, which remains essential for accessing the radio frequency (RF) spectrum and 5G new radio (NR)'s coexistence with current and emerging applications that are spectrally nearby.

The FBW of an acoustic filter is fundamentally set by the electromechanical coupling ( $k_t^2$ ) of the resonators in the filter.  $k_t^2$  measures the efficiency of electromechanical transduction, which limits the FBW similarly to the inter-resonator coupling limiting the FBW of a filter consisting of inter-coupled resonators. Considering the commonly used ladder filter topology, its maximum FBW is limited by the spectral separation between the series and parallel resonances of the comprising resonators, which is determined by the  $k_t^2$  [8]:

$$FBW \approx \sqrt{(12/\pi^2)k_t^2 + 1} - 1 \quad (1)$$

Currently, surface acoustic wave (SAW) resonators and aluminum nitride (AlN) thin-film bulk acoustic resonators (FBARs) are the commercial solutions for front-end filters and multiplexers. SAW devices, which typically operate below 3 GHz, are challenging to be scaled up in frequency without sacrificing performance [9]–[12]. In addition, their  $k_t^2$  is typically around 8%, which implies an FBW of less than 4.7% based on Eq. 1. AlN FBARs, despite having been demonstrated with high  $Q$  at all sub-6GHz frequencies, are fundamentally limited in  $k_t^2$  by the piezoelectric coefficients of sputtered polycrystalline AlN [13]–[15]. Although  $k_t^2$  can be enhanced with Sc-doped AlN films [16], [17], the enhancement comes at the cost of much-reduced  $Q$  (possibly due to

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the inclusions induced by dopants [18], [19]), thus resulting in overall degradation in the device figure of merit ( $\text{FoM} = k_t^2 \cdot Q$ ) and filter insertion loss (IL). To circumvent the limitations set by  $k_t^2$ , other filters topologies that combine reactive elements, lumped [20], distributed [21], or integrated passives device (IPD) [22] with acoustic resonators have been proposed to enlarge the filter BW. These approaches typically resort to an inductive element (or its equivalent) connected in parallel with the acoustic resonator to move the series and anti-resonances of the collective circuit (resonator and inductor) further apart. At sub-1.5 GHz, it requires a large inductance and thus leads to a large filter footprint. At higher frequencies, the inductance is smaller but typically with a lower  $Q$ , degrading the IL, out-of-band rejection, and roll-off. Moreover, the final hybrid circuit still requires high  $k_t^2$  devices to meet the very large FBW (e.g. n77-n79) of 5G NR. To simultaneously achieve low IL, large FBW, sharp out-of-band rejection, and steep skirt for 5G filters, acoustic resonators have to be developed with concurrent high  $k_t^2$  and  $Q$ , and large FoM up to 6 GHz.

Recently, Lamb wave acoustic or MEMS resonators based on single-crystal X-, Y-, and Z-cut LiNbO<sub>3</sub> thin films are receiving increasing research attention and several reported demonstrations have broken the records of FoM due to their high  $k_t^2$  (>20%) and low damping loss [23]–[29]. Despite the demonstrated high FoMs of these Lamb wave mode devices, their moderate phase velocities, 6000 m/s for S0 and 3500 m/s for SH0, make it difficult to cover the entire sub-6 GHz spectrum. To utilize the high piezoelectric coefficients of LiNbO<sub>3</sub> material in sub-6 GHz spectrum, the first-order antisymmetric (A1) Lamb-wave mode, which has a very large phase velocity in single-crystal Z-cut LiNbO<sub>3</sub> thin films [30], was demonstrated at 5 GHz with a FoM of 153 and  $f \cdot Q$  product of  $2.3 \times 10^{12}$  [31]–[33]. In spite of the large FoM in the aforementioned demonstrations,  $Q$ s of these devices are still far from the anticipated value of single-crystal LiNbO<sub>3</sub> devices at GHz frequencies. Moreover, the spurious modes near the pass-band remain a major bottleneck as they lower  $k_t^2$  of the intended resonance and create in-band ripples and out-of-band spurious responses.

In this study, we exploit the first-order antisymmetric (A1) mode in a transferred Y-cut LiNbO<sub>3</sub> thin film with the aim to enhance FoM and  $f \cdot Q$ , and to suppress the significant spurious modes concurrently. To this end, the resonant frequency, phase velocity, coupling factor, and excitation of the A1 mode are first carefully analyzed. The origins of spurious modes are identified, subsequently leading to their mitigation methods based on electrode design optimization. The final device design feature multiple pairs of electrodes with wide gaps between electrodes to quasi-exclusively harness the piezoelectric transduction for the intended mode. To validate our analysis and modeling, different designs of devices are fabricated on a 1.2  $\mu\text{m}$  thick Y-cut LiNbO<sub>3</sub> thin film, and the optimized device is measured with a resonance at 1.65 GHz, a high  $k_t^2$  of 14%, a high  $Q$  of 3112, and a near spurious-free response. As listed in Table I, the high FoM demonstrated in our design, which is collectively enabled by high  $k_t^2$  and  $Q$ , and the spurious-free response, surpasses state-of-the-art (SOA) technologies in the

TABLE I  
PERFORMANCE COMPARISON OF THE STATE-OF-THE-ART

Mat. & mode	$f$ (GHz)	$k_t^2$ (%)	$Q$	FoM	$f \cdot Q$
LiTaO <sub>3</sub> SAW [9]	2	7	1000	70	$2.0 \times 10^{12}$
I.H.P SAW [10]	1.9	8	4000	320	$7.6 \times 10^{12}$
I.H.P SAW [10]	3.5	8	1900	152	$6.65 \times 10^{12}$
AlN FBAR [14]	2	4.7	3670	172	$7.34 \times 10^{12}$
AlN FBAR [13]	5.1	6.4	913	58.4	$4.56 \times 10^{12}$
Sc-AlN LVR [17]	0.53	4.5%	1240	56	$0.66 \times 10^{12}$
LiNbO <sub>3</sub> LVR [24]	0.5	21.7%	1300	280	$0.65 \times 10^{12}$
LiNbO <sub>3</sub> A1 [31]	4.35	29%	527	153	$2.3 \times 10^{12}$
<b>This work</b>	<b>1.65</b>	<b>14%</b>	<b>3112</b>	<b>435</b>	<b><math>5.1 \times 10^{12}</math></b>

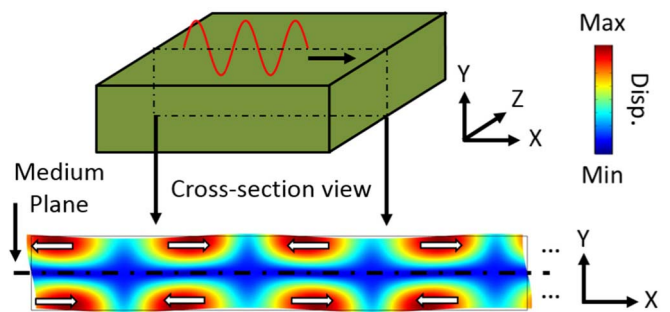


Fig. 1. Cross-sectional view of the displacement mode shape of the A1 mode propagating in a Y-cut LiNbO<sub>3</sub> slab. Y-cut LiNbO<sub>3</sub> slab has mechanically free top and bottom surfaces and periodic boundaries in the lateral direction. The arrows denote the displacement directions.

sub-6 GHz frequency range. These types of devices have shown strong potential for enabling high-performance miniaturized filters for future 5G front-ends.

## II. THEORETICAL ANALYSIS AND MODELING

### A. First-Order Antisymmetric (A1) Lamb Wave Mode

Antisymmetric Lamb wave modes are a class of Lamb-wave modes characterized by their particular anti-symmetry about the median plane of the plate. In other words, they have equal vertical displacement components but opposite longitudinal components on opposite sides of the median plane [34]. The order ( $n$ ) of the antisymmetric Lamb wave modes is defined based on the relationship among cut-off frequency ( $f_c$ ), wave velocity in the thickness direction ( $v_t$ ), and the plate thickness ( $t$ ) [34]:

$$f_c \times 2t = (2n - 1) \times v_t \quad (2)$$

So the first-order ( $n = 1$ ) antisymmetric Lamb wave mode has a cut-off frequency equal to half the ratio between the wave velocity in the thickness direction and the plate thickness, and its Comsol-simulated eigenmode is shown in Fig. 1.

### B. Design Parameters of A1

To more precisely predict the resonant frequency, we have to resort to a more refined model that treats the cross-section

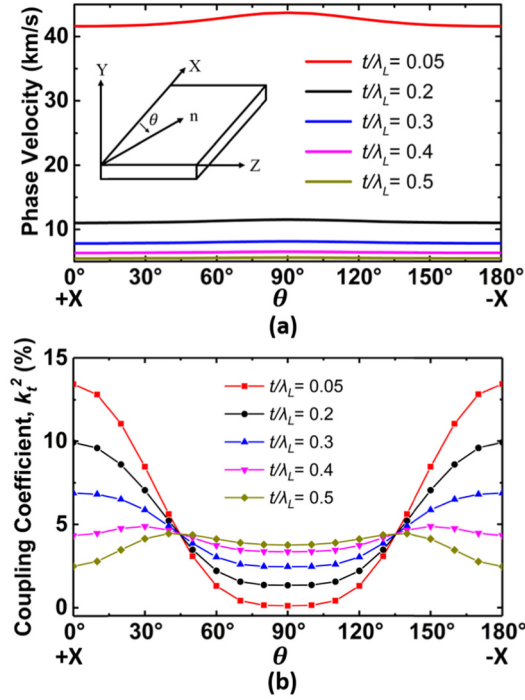


Fig. 2. Calculated (a) phase velocity and (b) electromechanical coupling coefficient ( $k_t^2$ ) of the first-order antisymmetric (A1) Lamb-wave in a Y-cut LiNbO<sub>3</sub> thin film vs. the propagation direction for different ratios of film thickness to longitudinal wavelength ( $t/\lambda_L$ ).

of the resonator as a two-dimensional cavity. The center frequency is then determined by the thickness of the thin film and the lateral dimensions of the motional cavity. The resonant frequency of A1 in a two-dimensional cavity with a thickness of  $t$  and width of  $G$  is given by

$$f_0 = \frac{v_L}{2t} \sqrt{\alpha^2 + \left(\frac{t}{G}\right)^2} \quad (3)$$

where  $G$  is equal to half of the longitudinal wavelength ( $\lambda_L/2$ ) and  $\alpha$  is the ratio between the velocity of vertical and longitudinal directions:

$$\alpha = \sqrt{c_{55}/c_{11}} \quad (4)$$

where  $c_{11}$  and  $c_{55}$  are the stiffness constants [34].

Since LiNbO<sub>3</sub> is highly anisotropic, the device performance highly depends on the propagating orientations. To determine the optimal device orientation, the phase velocity of the A1 mode in Y-cut LiNbO<sub>3</sub> is first studied using COMSOL-based FEA. As shown in Fig. 2(a), the phase velocity is calculated as a function of the ratio between film thickness ( $t$ ) and longitudinal wavelength ( $\lambda_L$ ) with orientations varies from  $0^\circ$  to  $180^\circ$  to X-axis. The results suggest that the effect of orientations on phase velocity is small, and a smaller ratio of  $t/\lambda_L$  leads to a larger phase velocity. In addition to the phase velocity, the high electromechanical coupling coefficient ( $k_t^2$ ) can be attained at the optimal device orientation and with a preferred ratio of  $t/\lambda_L$ . As shown in Fig. 2(b), as the orientation varies from  $0^\circ$  to  $180^\circ$  to +X axis in the Y-cut plane,  $k_t^2$  changes with a maximum value along either the +X or -X-axis. Therefore, the devices in this work are all oriented

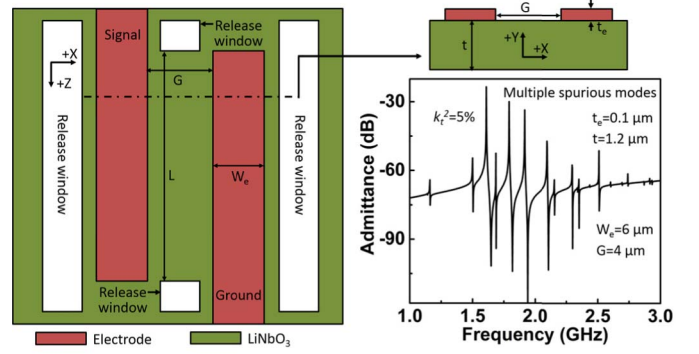


Fig. 3. Top and cross-section views of the Y-cut LiNbO<sub>3</sub> A1 mode resonator with FEA simulated response of an A1 mode resonator based on Y-cut LiNbO<sub>3</sub> (1.2  $\mu\text{m}$ ) with the conventional 2-electrode configuration.

along the +X axis. In addition to the device orientation, the ratio of  $t/\lambda_L$  also influences  $k_t^2$  as Fig. 2(b) clearly shows that a lower  $t/\lambda_L$  produces a higher  $k_t^2$ .

In this work, we focus on the resonance around 1.7 GHz as the first step to understand and demonstrate the performance of A1 mode resonators using Y-cut LiNbO<sub>3</sub> thin films. Future work will focus on higher resonant frequencies. Based on the above analyses, we choose the thickness of the thin film to be 1.2  $\mu\text{m}$  for the targeted resonant frequency.

### C. Excitation and Spurious Modes

In addition to the resonant frequency, the transducer, which can excite A1 mode in the Y-cut LiNbO<sub>3</sub> thin film efficiently, needs to be considered based on the piezoelectric coupling matrix of LiNbO<sub>3</sub>. Similar as the design in Z-cut LiNbO<sub>3</sub>, A1 mode needs the electric field in the same direction of wave propagation. The simplest transducers for such a purpose are interdigital electrodes that are patterned exclusively on top of the LiNbO<sub>3</sub> thin film, which promises the least fabrication complication and low cost in manufacturing. As shown in Fig. 3, the 2 interdigital electrodes, when connected to signal and ground respectively, induce lateral alternating electric fields in the mechanically suspended LiNbO<sub>3</sub> thin film, which subsequently excite the resonator into A1 mode vibration. The design parameters of this 2-electrode resonator, labeled in Fig. 3, are listed in the inset. To attain maximum  $k_t^2$ , based on the analysis of optimal device orientation, the interdigital electrodes are paralleled with the Z-axis to excite lateral electric fields along the X-axis (Fig. 3). However, as shown in the Comsol-based FEA-simulated response (Fig. 3), the simulated  $k_t^2$  is lower than the theoretical analysis and multiple unwanted spurious modes are excited near A1 mode. This is because the electric field excited by top interdigital electrodes within the thin film is non-uniform [35]–[37]. The non-uniform electric field introduces unwanted spurious modes, thus dispersing the transduction energy into various modes which lower the  $k_t^2$  of the targeted mode.

To understand the origins of unwanted spurious modes, the non-uniform electric field is studied. As seen in Fig. 4 (a), the FEA-simulated distribution of electric field excited by top interdigital electrodes shows that the electric field can be

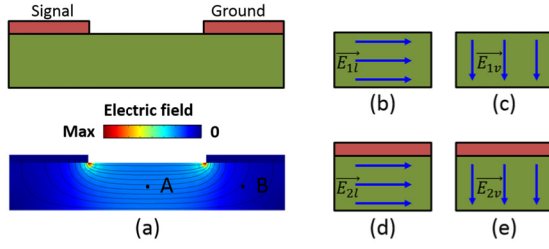


Fig. 4. (a) FEM-simulated result of electric field distribution with electric field lines. (b) Lateral and (c) vertical electric field in a section of the un-metalized LiNbO<sub>3</sub> thin film. (d) Lateral and (e) vertical electric field in a section of the metalized LiNbO<sub>3</sub> thin film.

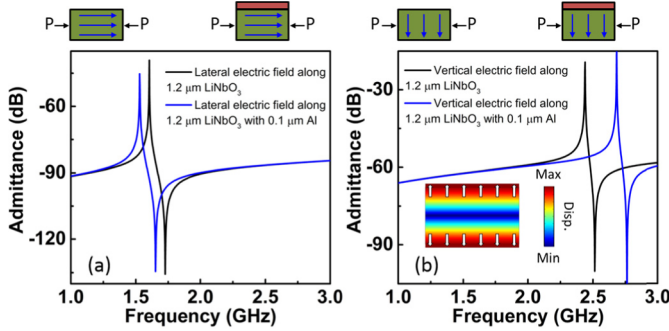


Fig. 5. Simulation structures with periodic boundaries and FEA-simulated results of the (a) A1 mode excited by the lateral electric field and (b) S1 mode excited by the vertical electric field in the sections of 1.2 μm LiNbO<sub>3</sub> thin film without and with 0.1 μm Al. The displacement mode shape of the S1 mode is included in the inset.

decomposed into lateral and vertical components in both the un-metalized (Point A) and metalized (Point B) sections of the LiNbO<sub>3</sub> thin films [Fig. 4(b)-(e)] [37]. To qualitatively understand the relationship between these E-field components and the spurious modes, idealized lateral and vertical electric fields are separately applied in the Y-cut LiNbO<sub>3</sub> thin films with periodic boundaries. As shown in Fig. 5 (a), one major unwanted spurious mode is the A1 sidetone excited by the lateral electric field in the section of the metalized LiNbO<sub>3</sub> thin film. This is because its resonant frequency is different from the targeted resonant frequency of the A1 mode which is excited by the lateral electric field in the section of the un-metalized LiNbO<sub>3</sub> thin film. The frequency difference is due to the change of equivalent stiffness and density after adding top electrodes [38]. As shown in Fig. 5 (b), other major unwanted spurious modes are the first-order symmetric modes (S1) excited by the vertical electric field in both the un-metalized and metalized sections of the LiNbO<sub>3</sub> thin film. The displacement mode shape of the S1 mode is shown in the inset of Fig. 5 (b).

In addition to the non-uniform electric field, the etched edges of the resonator body are another origin of the unwanted spurious modes. This is similar to SAW devices, these spurious modes are generated by the interference between desired waves and the reflected waves due to the mechanical free boundaries at the two lateral ends of the resonator body [39], [40]. As a comparison to the idealized situation, the periodic boundaries are replaced by free boundaries for the simulation

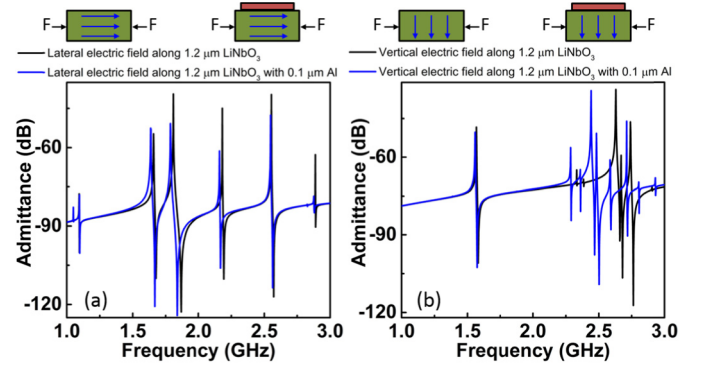


Fig. 6. Simulation structures with free boundaries and FEA-simulated results of the (a) A1 mode and spurious modes excited by the lateral electric field, and (b) S1 mode and spurious modes excited by the vertical electric field along 1.2 μm LiNbO<sub>3</sub> without and with 0.1 μm Al.

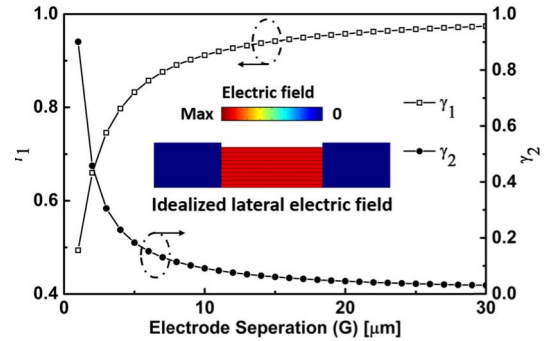


Fig. 7. Electric field strength ratios,  $\gamma_1$  and  $\gamma_2$ , as functions of the electrode separation (G).

in Fig. 6 to model the etched edges of the resonator body. Unlike the FEA-simulated results showed in Fig. 5, which has only one single mode for each structure, the admittance responses in Fig. 6 show the increased number of excited spurious modes and decreased value of  $k_t^2$  of the targeted mode. To achieve the enhancement of  $k_t^2$  and get rid of ripple responses of composed filters, these spurious modes need to be suppressed.

#### D. Suppression of Spurious Modes

Based on the above analysis, the spurious modes can be suppressed by optimizing the distribution of the electric field and decreasing the effect of the etched edges of the resonator body.

According to the simulation result in Fig. 4(a), the actual electric field has lateral and vertical components in the LiNbO<sub>3</sub> slab without and with top electrode [Fig. 4 (b)-(e)], and only the lateral electric field in LiNbO<sub>3</sub> slab without electrode ( $E_{1l}$ ) contribute to the excitation of targeted A1 mode, while other components generate unwanted spurious modes. In the point of energy, the device transduction efficiency ( $k_t^2$ ) in converting electrical energy to mechanical energy of different acoustic modes can be described by:

$$k_t^2 = \frac{U_{me}}{U_e + U_d} = \frac{\int T : d \cdot EdV}{\int T : s^E : TdV + \int E \cdot \epsilon^T \cdot EdV} \quad (5)$$

where  $U_{me}$  is the mutual energy,  $U_e$  is the elastic energy, and  $U_d$  is the electric energy.  $T$  is the stress tensor, and  $E$  is the electric field.  $d$ ,  $s^E$ , and  $\varepsilon^T$  denote the piezoelectric strain constants, compliance constants at a constant electric field, and permittivity constants at constant stress respectively. For the A1 mode, its  $k_t^2$  depends on the strength of effective lateral electric field ( $E_{1l}$ ):

$$U_{meA1} = \int T : d \cdot E_{1l} dV \quad (6)$$

while the  $k_t^2$  of spurious modes depends on the strength of  $E_{1v}$ ,  $E_{2l}$ , and  $E_{2v}$  [Fig. 4 (c)-(e)].

To suppress the spurious modes caused by the non-uniform electric field,  $E_{1v}$ ,  $E_{2l}$ , and  $E_{2v}$  should be decreased, and the simplest way is adjusting the electrode separation to optimize the electric field distribution. In our case, considering the limitation of lithography, the width of the electrodes is set to be  $4 \mu\text{m}$  to simplify the analysis. To quantify the effect of electrode separation, the strength of the electric field in point A [Fig. 4(a)], where the center of the resonator body is, is compared to the strength of an idealized lateral electric field ( $E_{idea}$ ) (as shown in the inset of Fig. 7) which is uniform and aligned in the lateral direction under the same potential:

$$\gamma_1 = |E_{1l}| / |E_{idea}| \quad (7)$$

Since  $E_{1l}$  and  $E_{idea}$  are excited under the same potential, the value of  $\gamma_1$  indicates the degree of idealization and the optimized design should have  $\gamma_1$  near equal to 1. To compare the strength of spurious modes and the targeted mode, the strength of  $E_{1v}$  at point A,  $E_{2l}$ , and  $E_{2v}$  at point B, where the center of the LiNbO<sub>3</sub> cavity covered by electrodes, is compared to the strength of  $E_{1l}$ :

$$\gamma_2 = (|E_{1v}| + |E_{2l}| + |E_{2v}|) / |E_{1l}| \quad (8)$$

Based on the above analysis, the optimized design should have a maximum  $\gamma_1$  and minimum  $\gamma_2$ . To find the relationships among  $\gamma_1$ ,  $\gamma_2$ , and electrode separation, the width of the top electrodes is fixed with  $4 \mu\text{m}$  in the FEA simulation considering the limitations of the lithography in the fabrication. As shown in Fig. 8, the data with electrode separation varied from 1 to  $30 \mu\text{m}$  shows that increasing the electrode separation can increase  $\gamma_1$  and decrease  $\gamma_2$  simultaneously, suggesting a larger electrode separation for better spurious modes suppression. To further validate the analysis, the resonators with the structure shown in Fig. 4 are simulated for different electrode separations. As shown in Fig. 8, most significant spurious modes are mitigated through increasing the gap between interdigital electrodes from  $4 \mu\text{m}$  [Fig. 8(a)] to  $14 \mu\text{m}$  [Fig. 8(b)].

To suppress the spurious modes caused by the etched edges of the resonator body, we can borrow the idea from SAW devices that it is well known to apply acoustic absorbers or reflecting gratings between the IDT and the edges of the substrate to suppress the reflected acoustic waves [41]. In the view of energy, the proportion of reflected acoustic energy at the etched edges can be decreased to lower the proportion of the energy of spurious modes. To this end, multi pairs of interdigital electrodes are used to concentrate

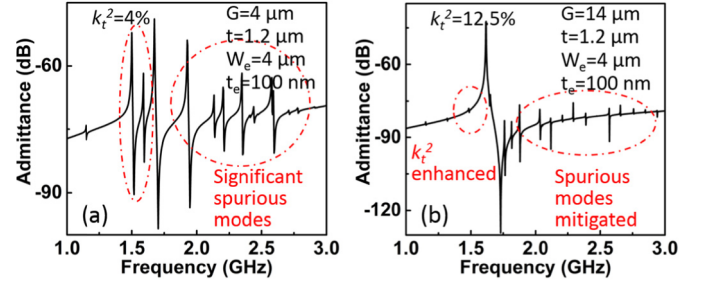


Fig. 8. FEA-simulated results of the devices with (a)  $G = 4 \mu\text{m}$  and (b)  $G = 14 \mu\text{m}$ .

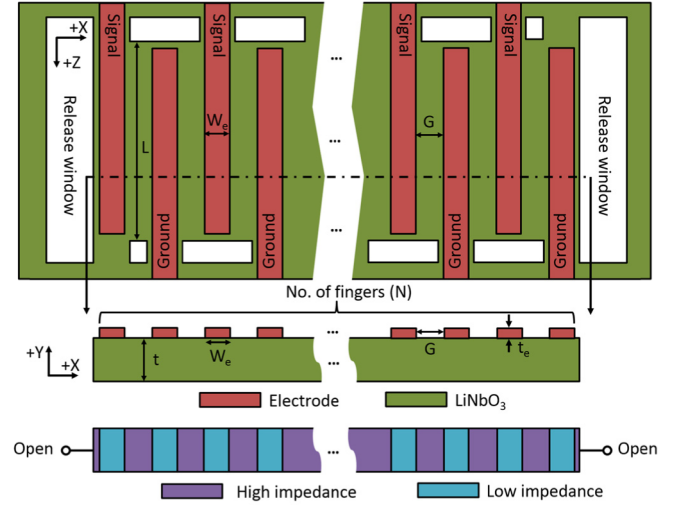


Fig. 9. Top and cross-section views of multi pairs of interdigital electrodes structure with the equivalent model of multi acoustic reflection sections.

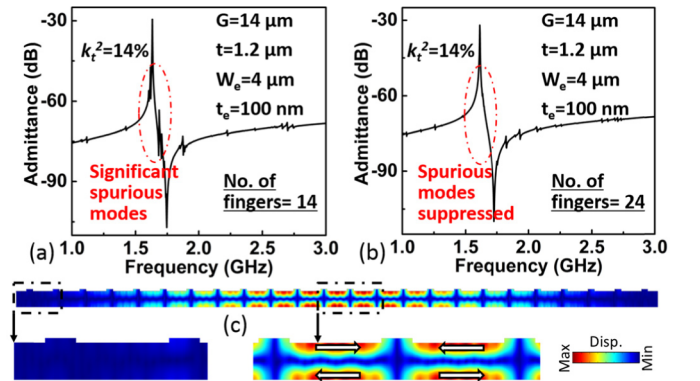


Fig. 10. FEA-simulated results of the devices with (a)  $N = 14$  and (b)  $N = 24$ . (c) Displacement mode shape of A1 mode excited in (b) with the zoomed-in views in the center and edge of the resonator body.

the acoustic energy in the lateral center of the resonator body. The LiNbO<sub>3</sub> sections without electrodes can be treated as high impedance sections, while the LiNbO<sub>3</sub> sections with electrodes can be treated as low impedance sections. As shown in Fig. 9, the whole resonator body can be modeled as the alternate connection of the high impedance sections and low impedance sections. The acoustic energy, transduced from electric energy by the interdigital electrodes, spreads in two lateral directions

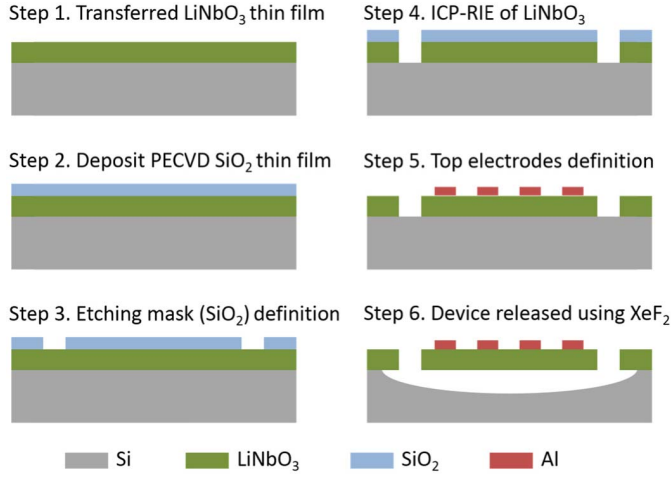


Fig. 11. Fabrication process for the Y-cut LiNbO<sub>3</sub> resonators.

from each high impedance section. As a result of reflection and transmission at each interface, the acoustic energy can be concentrated in the lateral center of the resonator body. Moreover, as the number of sections increases, the concentration of acoustic energy gradually becomes higher, and the proportion of reflected acoustic energy at edges becomes less. To validate the analysis of multi acoustic reflection sections, the resonators with different pairs of interdigital electrodes are simulated with 2D Comsol FEA. As shown in Fig. 10, most spurious modes can be suppressed by increasing the number of pairs to 24. The displacement mode shape of the device with 24 electrode fingers is shown in Fig. 10(c). The distribution of the amplitude of displacement confirms that the acoustic energy is concentrated in the lateral center of the resonator body. An optimal design is obtained with 24 electrodes and a 14  $\mu\text{m}$  electrode gap under the consideration of performance and size.

### III. EXPERIMENTAL RESULTS AND DISCUSSIONS

#### A. Device Fabrication

To validate the analysis and modeling results, A1 resonators were fabricated with the process shown in Fig. 11. In the first step, a 1.2  $\mu\text{m}$  thick Y-cut LiNbO<sub>3</sub> thin film was transferred onto a high resistivity Si wafer by NGK electronics. SiO<sub>2</sub> was then deposited via plasma-enhanced chemical vapor deposition (PECVD). In the third step, the PECVD SiO<sub>2</sub> was patterned with CHF<sub>3</sub>-based reactive ion etching (RIE), serving as a hard mask for etching LiNbO<sub>3</sub> thin film in step 4. To achieve high performance, the etching of LiNbO<sub>3</sub> was done by Cl<sub>2</sub>-BCl<sub>3</sub>-based RIE with inductively coupled plasma (ICP) to guarantee the straight etching profile. Afterward, the hard mask (SiO<sub>2</sub>) is removed with HF, and 120 nm-thick Aluminum is subsequently defined as top electrodes on top of the LiNbO<sub>3</sub> thin film via a lift-off process. In the last step of the process, the Si under LiNbO<sub>3</sub> was removed with XeF<sub>2</sub>-based dry etching to suspend the resonators.

The SEMs of different fabricated devices are shown in Fig. 12. As shown in Fig. 12(f), the etched sidewall, which

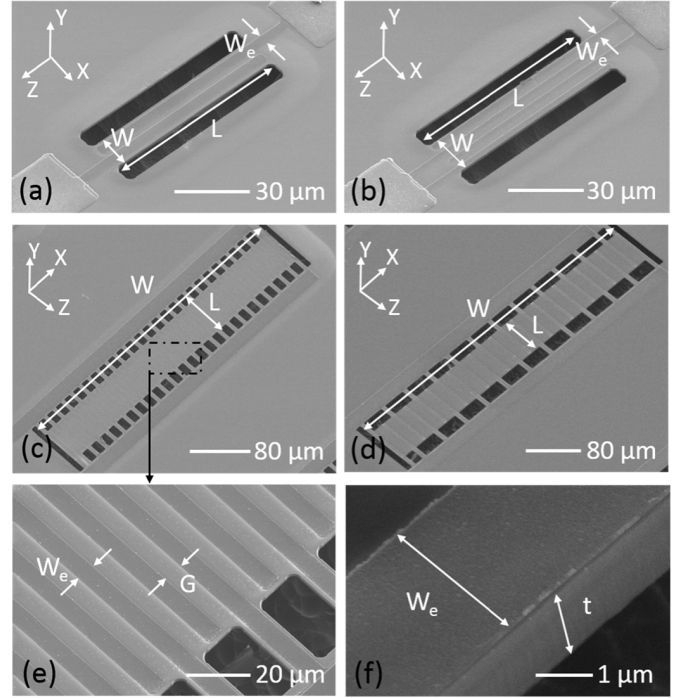


Fig. 12. SEM images of the (a) 2-electrode device, (b) 4-electrode device, (c) 52-electrode device, (d) 24-electrode device, (e) Zoomed-in view of multi-electrode device, and (f) sidewall of the etched LiNbO<sub>3</sub> thin film.

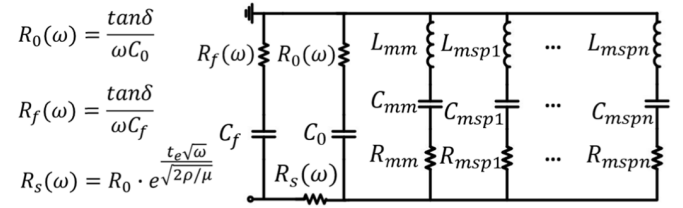


Fig. 13. Multi-resonance MBVD circuit model with multiple motional branches capturing the primary mode and spurious modes.

serves as the acoustic boundary, has an angle of near 90°. According to previous work [42], straight acoustic boundaries lead to high-Q performance.

#### B. Extraction of Parameters

According to previous work, the effect of spurious modes should be accounted for in fitting to increase the accuracy of extraction [43]. A multi-resonance modified Butterworth-Van Dyke (MBVD) model, in which the resonances of main mode and significant spurious modes are captured by a motional branch of  $R_m$ ,  $L_m$ , and  $C_m$ , is used to interpret the measurement results. As shown in Fig.13, the motional branch of the main mode is captured by  $R_{mm}$ ,  $L_{mm}$ , and  $C_{mm}$ , while the motional branches of different spurious modes are captured by  $R_{mspn}$ ,  $L_{mspn}$ , and  $C_{mspn}$ . The surface resistance of electrodes and leading lines are accounted for by adding resistor ( $R_s$ ) in series, the value of which is depended on frequency due to the skin effect and calculated based on the equation shown in Fig. 13. To account for the parasitic effects,  $C_f$  and  $R_f$

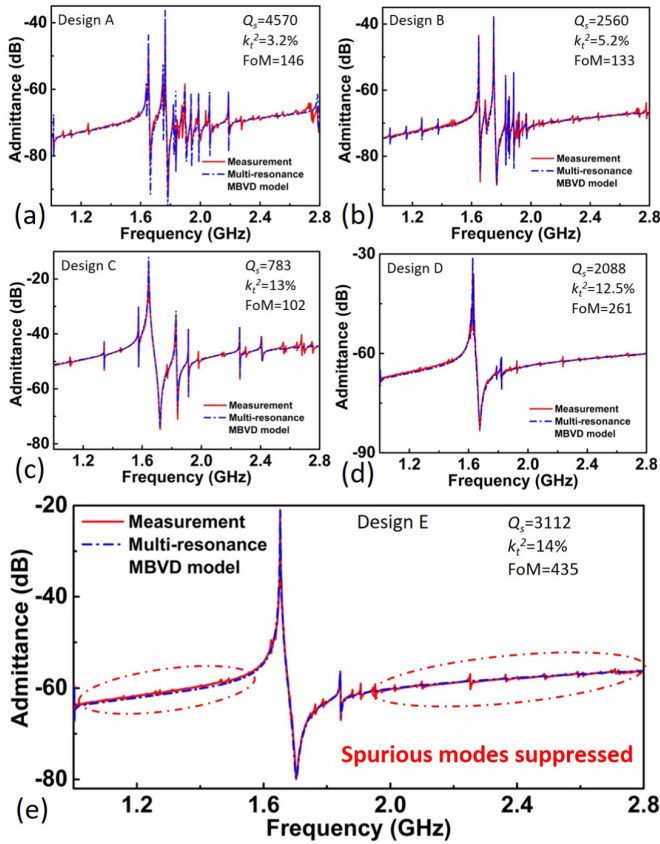


Fig. 14. Measurement results of various designs: (a) A, (b) B, (c) C, (d) D, and (e) E. The parameters and measured key values of these designs are listed in Table II.

are included as the feedthrough capacitance and loss in the substrate ( $\tan\delta$ ), respectively.

### C. Measured Admittance Responses

The fabricated devices were characterized at room temperature with a Keysight N5249A PNA network analyzer. The measured admittance responses of 5 different designs are shown in Fig. 14. Excellent agreement has been reached between the theoretical analysis and measurements. As shown in Fig. 14(a), the design A with two electrodes and a gap of  $4\ \mu\text{m}$  shows  $k_t^2$  of only 3%, which is far below the theoretical value [Fig. 2(b)] due to the dispersing of energy into various modes. To attenuate the acoustic energy of reflection-producing spurious modes, multiple electrodes are used in design B and C. The design B [Fig. 14(b)] with 4 electrodes shows  $k_t^2$  of 5.2% and the design C [Fig. 14(c)] with 52 electrodes shows  $k_t^2$  of 13%. The increasing of  $k_t^2$  indicates the attenuation of spurious modes, while there are still some significant spurious in the admittance response of design C due to the non-uniform electric field. The electrodes separation of  $14\ \mu\text{m}$  is used in the design D and E to make the electric field, excited by top electrodes, close to the idealized lateral electric field. The difference between design D and E is the number of electrodes. The design D with 14 electrodes shows  $k_t^2$  of 12.5%, and the design E with 24 electrodes, which exhibit notably suppression of spurious modes, shows

TABLE II  
DESIGN PARAMETERS AND MEASURED KEY VALUES  
OF THE FABRICATED A1 DEVICES

Design	A	B	C	D	E
$W\ (\mu\text{m})$	18	32	424	242	422
$N$	2	4	52	14	24
$G\ (\mu\text{m})$	4	4	4	14	14
$W_c\ (\mu\text{m})$	6	4	4	4	4
$L\ (\mu\text{m})$	80	80	80	80	80
$t\ (\mu\text{m})$	1.2	1.2	1.2	1.2	1.2
$t_e\ (\text{nm})$	100	100	100	100	100
$R_m + R_s\ (\Omega)$	63	74	4	35	11
$f_0\ (\text{GHz})$	1.75	1.75	1.65	1.65	<b>1.65</b>
$k_t^2$	3%	5.2%	13%	12.5%	<b>14%</b>
$Q_s$	4570	2560	783	2088	<b>3112</b>
FoM	146	133	102	261	<b>435</b>

$k_t^2$  of 14%. In addition to the spurious mode suppression, the  $Q_s$  also gets enhanced up to 3112 in the optimized design E [Fig. 14(e)].

Based on the comparison of all these five designs, by employing wider gaps (larger  $\gamma_1$  and smaller  $\gamma_2$ ) and multi-pairs of electrodes, all significant spurious modes are suppressed, and the FoM is notably enhanced. Parameters and measured key values of these five different designs are listed in Table II.

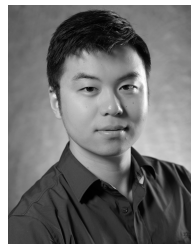
## IV. CONCLUSION

In this work, A1 mode LiNbO<sub>3</sub> MEMS resonators have been presented and the optimized design has been demonstrated at 1.65 GHz with an FoM as high as 435, an  $f \cdot Q$  product of  $5.1 \times 10^{12}$  Hz and a near spurious-free response. Different configurations of electrodes have also been explored for achieving high FoMs and spurious-free response. The A1 Y-cut LiNbO<sub>3</sub> MEMS resonators have shown strong potential for enabling higher performance filters for next-generation RF front-ends.

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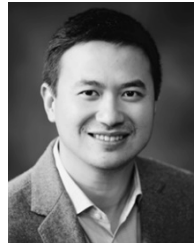
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